



INTERLABORATORY COMPARISON OF NOISE-PARAMETER MEASUREMENTS ON CMOS DEVICES WITH 0.12 μ m GATE LENGTH

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I. INTRODUCTION



The “Kelvin” Project:

- What is it?
 - Regular, small-group collaboration between IBM, RFMD and NIST to explore noise in IBM CMRF 8SF (0.13 μ m)
 - Aimed at developing working relationship, combining skills and allowing customer to gain experience with this technology
- Goals:
 - Develop new device, circuit and test structure designs over several MPWs
 - Explore means of improving data quality
 - Examine features and quirks of data to understand new physics and/or provide feedback to modeling
- Participants:
 - IBM: technology knowledge, device/modeling/RF test experience
 - David Greenberg, Susan Sweeney, Larry Wagner, Sebastian Csutak, Jack Pekarik
 - RFMD: Circuit design and test, modeling, product knowledge
 - Tom McKay, Ali Rezvani, Leonard Reynolds, Jon Tao, Judah Mendez
 - NIST: RF test innovation and standardization
 - Jim Randa, David Walker

Interest in CMOS:



- Relatively inexpensive: “mature” technology, extensive infrastructure (facilities, processes, models) already in place.
- Integration advantages: combine RF + digital on same chip
- Big IF is performance at higher frequencies.
- Several factors: speed, transmission line losses, difficulty getting good inductors ...
- Also must characterize noise performance of CMOS devices at RF (and above), especially for very small devices (since that’s what will be used).

Measurement Challenges:



- Very low minimum noise figure or noise temperature
- Very poorly matched; $|S_{11}|$, $|S_{22}|$, and $|\Gamma_{opt}|$ can all be greater than 0.7, and are often greater than 0.9.
- Even probe contact to pads (Al) is potentially problematic if vibration present.

This Paper:

- Measure “same” device (different dies) at all three labs & compare
 - S-parameters
 - Noise parameters

II. MEASUREMENTS

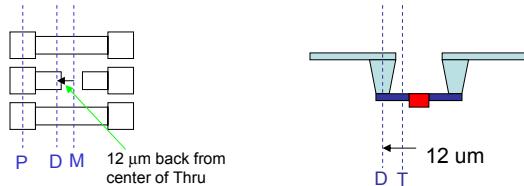
NIST
NOISE

The Device

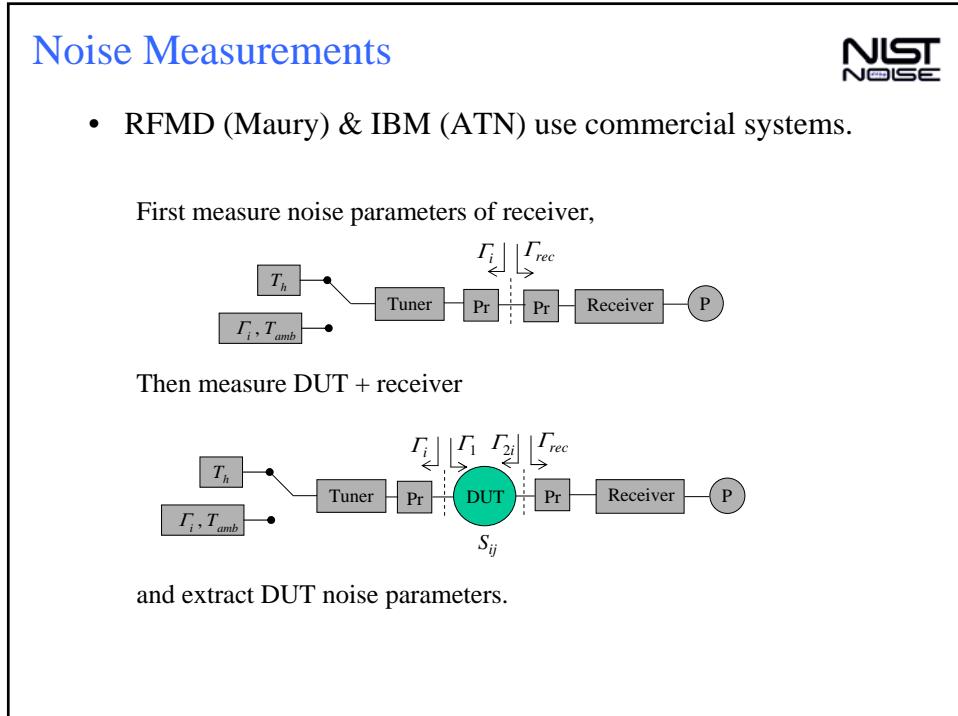
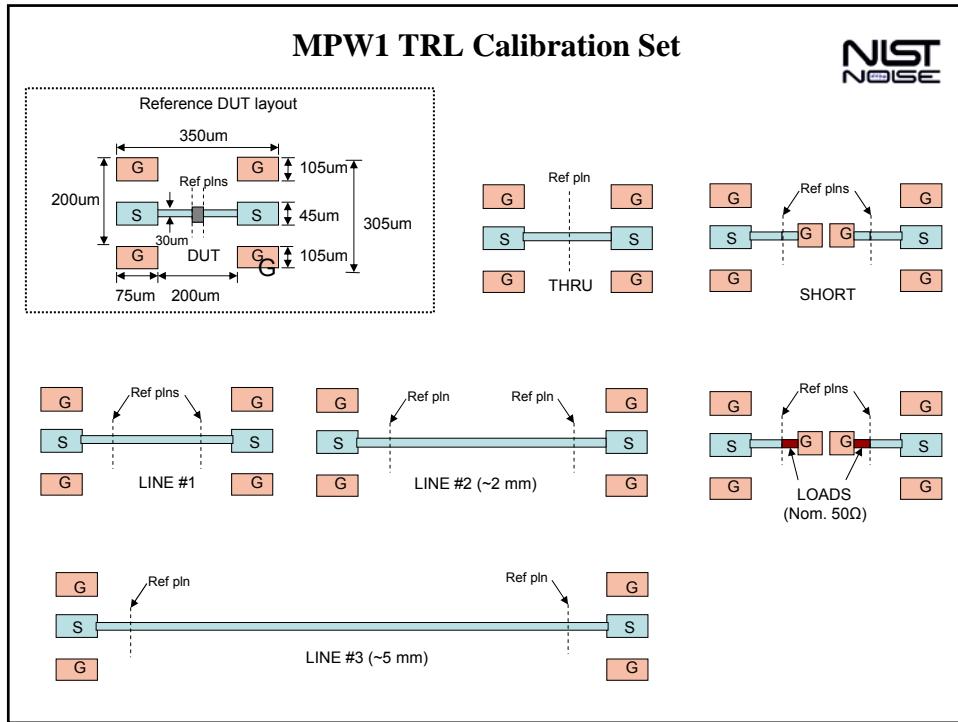
- 128×3×0.12 NMOS device
 - 128 fingers of polysilicon over
 - 3 μm wide active channel
 - 0.12 μm gate length
 - fabricated in 0.13 μm technology (by IBM)
- Bias:
 - drain voltage $V_{ds} = 1.2 \text{ V}$
 - $J = 25 \mu\text{A}/\mu\text{m}$

Calibration & Reference Planes

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NOISE

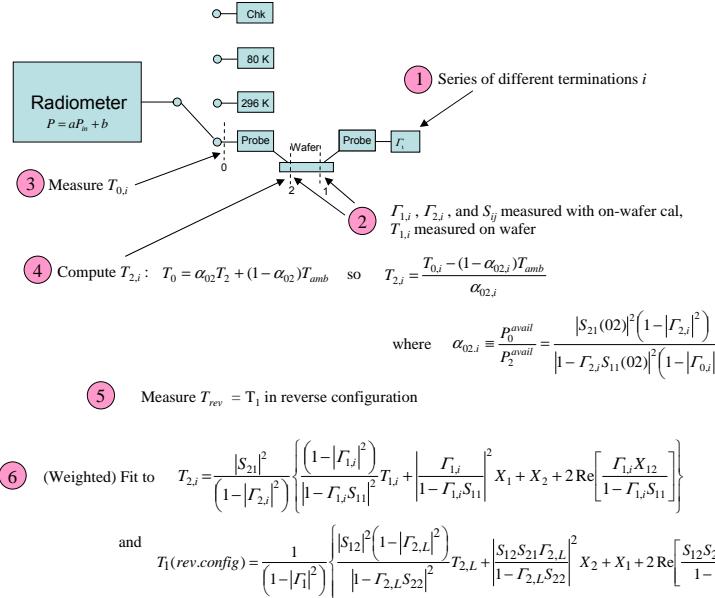


- RFMD & IBM:
 - Probe-tip cal at ref planes P with off-wafer standards + deembed to planes T
 - Also multiline TRL with on-wafer standards at planes D
- NIST:
 - multiline TRL with on-wafer standards at planes D



- NIST uses a radiometer-based method similar to its method for packaged amplifiers:

NIST
NOISE



- The X 's are essentially the elements of the noise matrix in the wave representation,

NIST
NOISE

$$k_B X_1 \equiv \langle |c_1|^2 \rangle \quad k_B X_2 \equiv \langle |c_2 / S_{21}|^2 \rangle, \quad k_B X_{12} \equiv \langle c_1 (c_2 / S_{21})^* \rangle$$

They can be written in terms of the conventional IEEE noise parameters (& vice versa).

- The NIST uncertainties are evaluated with a Monte-Carlo routine developed for amplifiers & modified to accommodate large $|S_{11}|$, $|S_{22}|$, and $|T_{opt}|$.

X's → IEEE

$$t = X_1 + |1 + S_{11}|^2 X_2 - 2 \operatorname{Re}[(1 + S_{11})^* X_{12}],$$

$$T_{e,\min} = \frac{X_2 - |\Gamma_{opt}|^2 [X_1 + |S_{11}|^2 X_2 - 2 \operatorname{Re}(S_{11}^* X_{12})]}{\left(1 + |\Gamma_{opt}|^2\right)},$$

$$\Gamma_{opt} = \frac{\eta}{2} \left(1 - \sqrt{1 - \frac{4}{|\eta|^2}}\right),$$

$$\eta = \frac{X_2 (1 + |S_{11}|^2) + X_1 - 2 \operatorname{Re}(S_{11}^* X_{12})}{(X_2 S_{11} - X_{12})}.$$

IEEE → X's

$$X_1 = T_{e,\min} \left(|S_{11}|^2 - 1 \right) + \frac{t |1 - S_{11} \Gamma_{opt}|^2}{|1 + \Gamma_{opt}|^2},$$

$$X_2 = T_{e,\min} + \frac{t |\Gamma_{opt}|^2}{|1 + \Gamma_{opt}|^2},$$

$$X_{12} = S_{11} T_{e,\min} - \frac{t \Gamma_{opt}^* (1 - S_{11} \Gamma_{opt})}{|1 + \Gamma_{opt}|^2}.$$

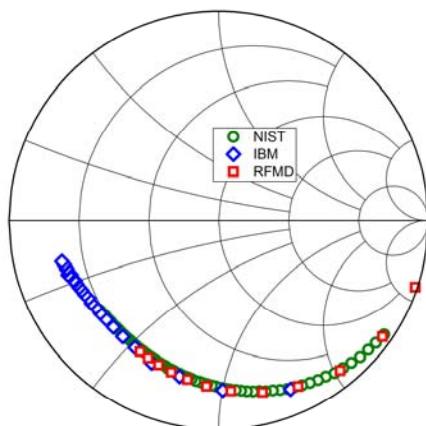
Notes:

$$X_2 = T_{e,0}$$

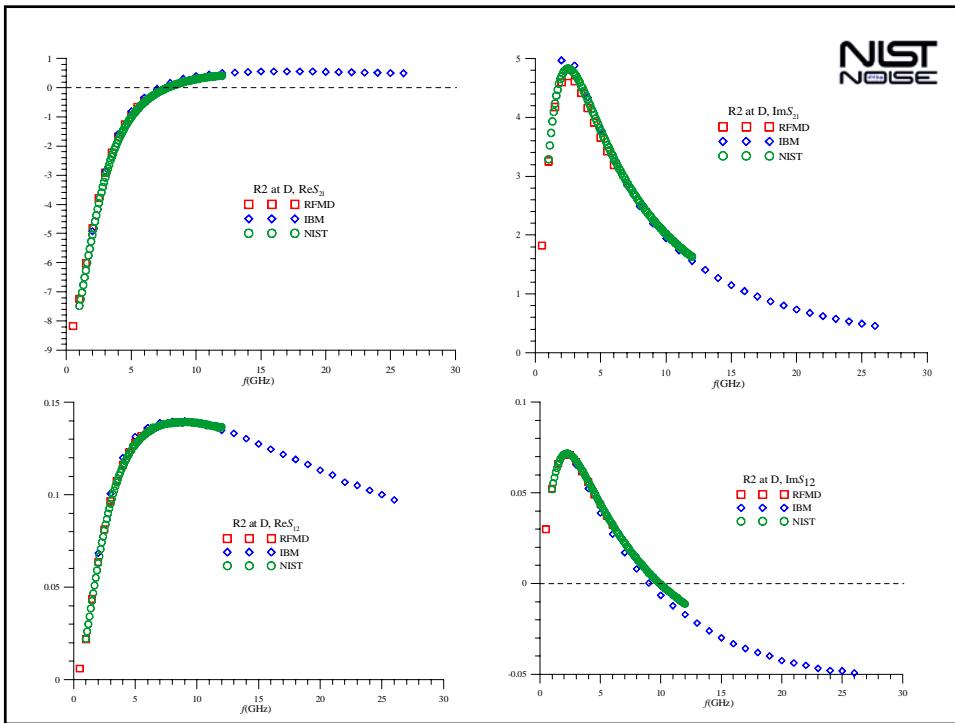
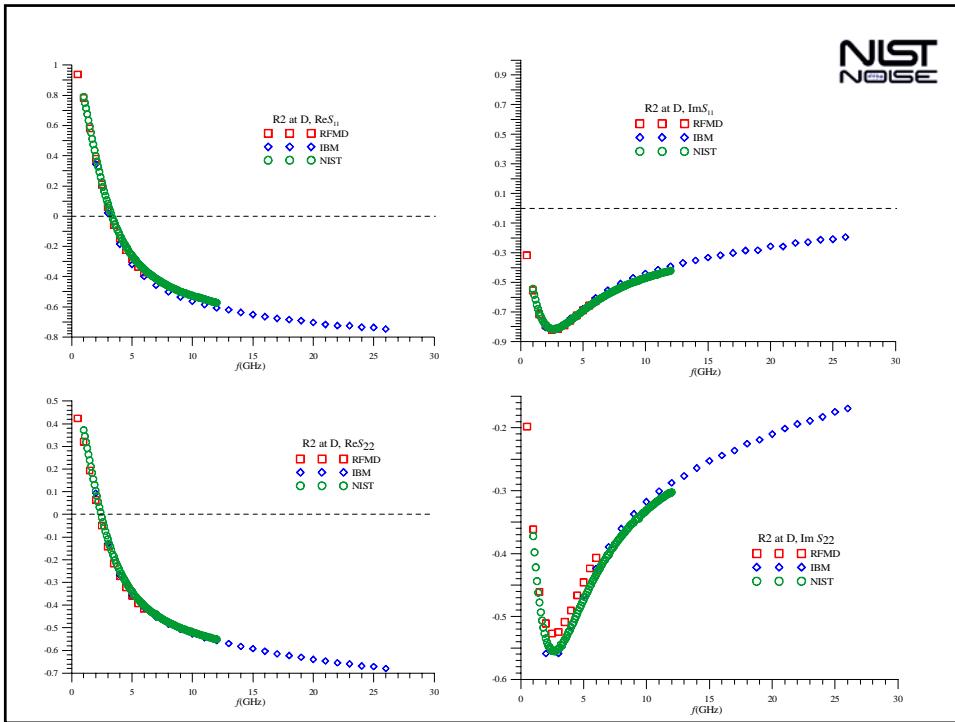
Bound implied by $X_1 \geq 0$

III. RESULTS

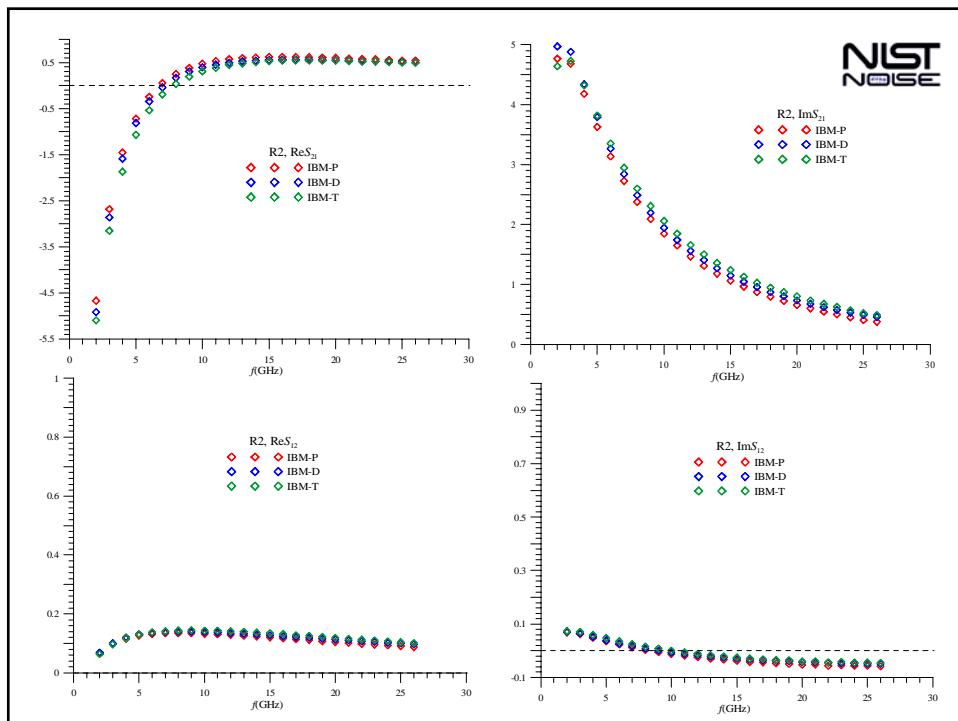
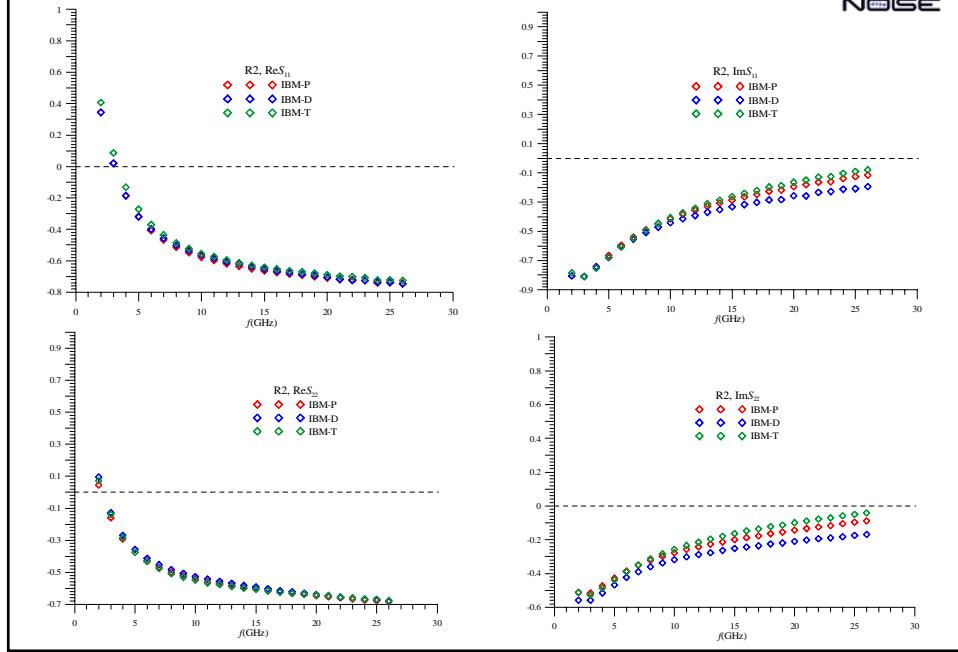
S Parameters:



S_{11} at plane D

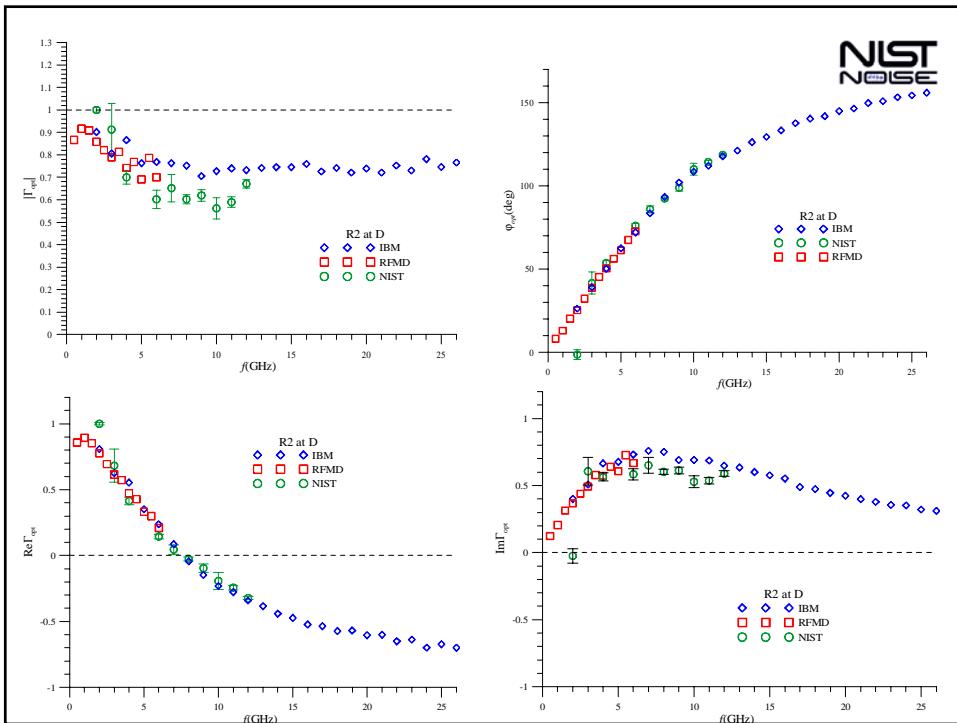
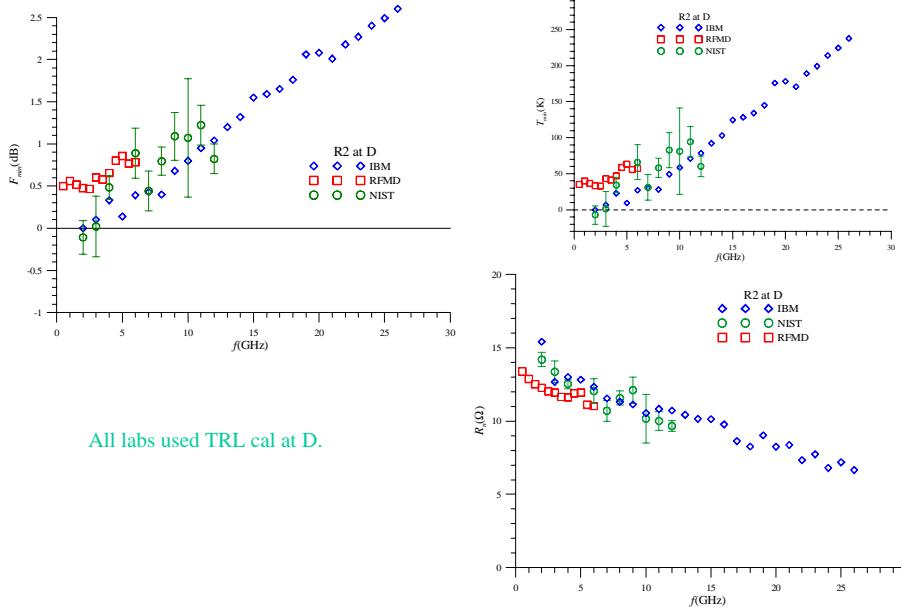


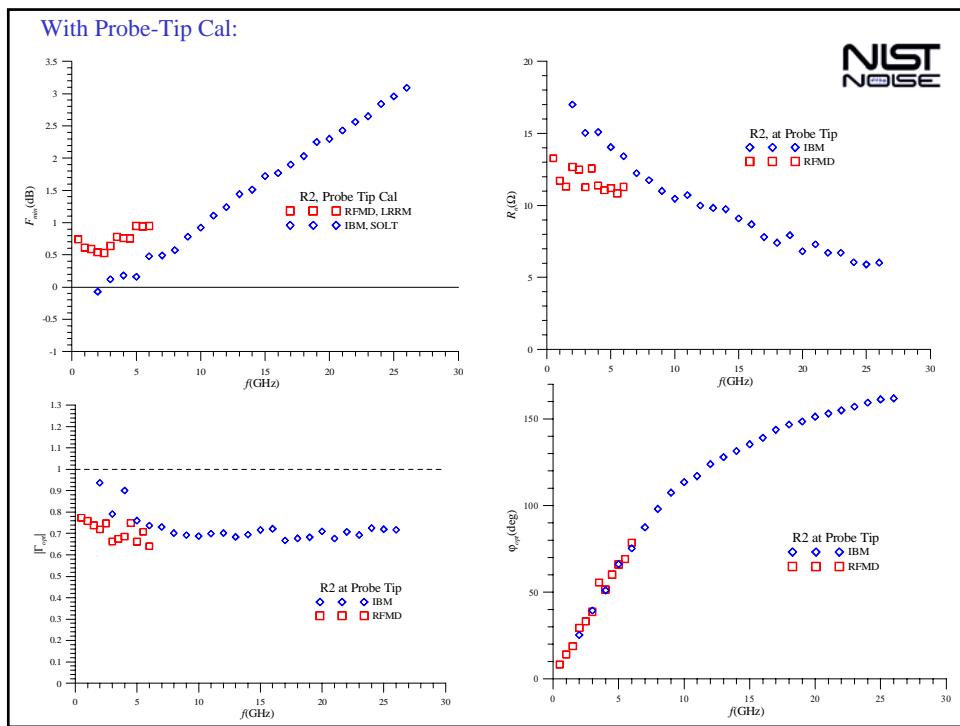
Comparison of different reference planes:



Noise Parameters (at D):

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IV. DISCUSSION

Conclusions:

- S-parameter measurements are in good agreement.
- Noise-parameter agreement is not as good
 - no really egregious conflicts
 - agreement probably within uncertainties
 - need smaller uncertainties, improved methods

Possible Improvements:

- Better calibration of hot noise source (RFMD & IBM)
- Input terminations (NIST)
 - bigger & better set
 - switch rather than manually change
- Use cold noise source on input (all)
- Additional reverse measurements
- Monte Carlo uncertainty analysis for RFMD & IBM